SN74LV374A-Q1 OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH 3-STATE OUTPUTS

SCLS468C - FEBRUARY 2003 - REVISED JANUARY 2008

Qualified for Automotive Applications Typical V (Output Ground Bounce)	PW PACKAGE (TOP VIEW)					
 Typical V_{OLP} (Output Ground Bounce) <0.8 V at V_{CC} = 3.3 V, T_A = 25°C 	OE 1	7 ₂₀ V _{CC}				
 Typical V_{OHV} (Output V_{OH} Undershoot) 	1Q 🛮 2	19] 8Q				
$>2.3 \text{ V at V}_{CC} = 3.3 \text{ V}, T_A = 25^{\circ}\text{C}$	1D 🛮 3	18 🛮 8D				
 Supports Mixed-Mode Voltage Operation on 	2D 🛮 4	17 🛮 7D				
All Ports	2Q 🛮 5	16 🛮 7Q				
 I_{off} Supports Partial-Power-Down Mode 	3Q 🛮 6	15 🛮 6Q				
Operation	3D 🛮 7	14 🛮 6D				
ESD Protection Exceeds JESD 22	4D 🛮 8	13 🛮 5D				
- 2000-V Human-Body Model (A114-A)	4Q ∐ 9	12 📙 5Q				
- 200-V Machine Model (A115-A)	GND [10	11 CLK				

description/ordering information

- 1000-V Charged-Device Model (C101)

The SN74LV374A is an octal edge-triggered D-type flip-flop designed for 2-V to 5.5-V V_{CC} operation.

This device features 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. It is particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

On the positive transition of the clock (CLK) input, the Q outputs are set to the logic levels set up at the data (D) inputs.

A buffered output-enable (OE) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without need for interface or pullup components.

OE does not affect internal operations of the latch. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

ORDERING INFORMATION†

TA	PACK	AGE‡	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 105°C	TSSOP – PW	Tape and reel	SN74LV374ATPWRQ1	LV374ATQ

[†] For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



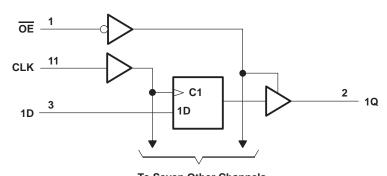
[‡]Package drawings, thermal data, and symbolization are available at http://www.ti.com/packaging.

SCLS468C - FEBRUARY 2003 - REVISED JANUARY 2008

FUNCTION TABLE (each flip-flop)

	INPUTS		OUTPUT
OE	CLK	D	Q
L	↑	Н	Н
L	\uparrow	L	L
L	L	Χ	Q_0
Н	X	Χ	Z

logic diagram (positive logic)



To Seven Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input voltage range, V _I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high-impedance or	
power-off state, V _O (see Note 1)	–0.5 V to 7 V
Output voltage range, V _O (see Notes 1 and 2)	\dots -0.5 V to V _{CC} + 0.5 V
Input clamp current, I _{IK} (V _I < 0)	–20 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±35 mA
Continuous current through V _{CC} or GND	±70 mA
Package thermal impedance, θ _{JA} (see Note 3)	83°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. This value is limited to 5.5 V maximum.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.



recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
Vcc	Supply voltage		2	5.5	V
		V _{CC} = 2 V	1.5		
.,	LPak Leval Count colleges	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	V _{CC} ×0.7		V
۷IH	High-level input voltage	V _{CC} = 3 V to 3.6 V	V _{CC} ×0.7		V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	V _{CC} ×0.7		
		V _{CC} = 2 V		0.5	
V/	Lauran in a tradition of the sea	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		$V_{CC} \times 0.3$	V
V _{IH} ! V _{IL} ! V _O Ω I _{OH} ! Δt/Δv !	Low-level input voltage	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		$V_{CC} \times 0.3$	V
		VCC = 2 V			
٧ _I	Input voltage		0	5.5	V
\/ -	Output valtage	High or low state	0	VCC	V
VO	Output voltage	3-state	0	5.5	V
		V _{CC} = 2 V		-50	μΑ
	High lovel output ourrent	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		-2	
ЮН	High-level output current	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		-8	mA
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		-16	
		V _{CC} = 2 V		50	μΑ
1	Lauran autorit autorit	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		2	
IOL	Low-level output current	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		8	mA
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		16	
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		200	
$\Delta t/\Delta v$	Input transition rise or fall rate	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		100	ns/V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		20	
TA	Operating free-air temperature	·	-40	105	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
	I _{OH} = -50 μA	2 V to 5.5 V	V _{CC} -0.1			
V	$I_{OH} = -2 \text{ mA}$	2.3 V	2			.,
VOH	$I_{OH} = -8 \text{ mA}$	3 V	2.48			V
	$I_{OH} = -16 \text{ mA}$	4.5 V	3.8			
	I _{OL} = 50 μA	2 V to 5.5 V			0.1	
.,	I _{OL} = 2 mA	2.3 V			0.4	.,
V _{OL}	I _{OL} = 8 mA	3 V			0.44	V
	I _{OL} = 16 mA	4.5 V			0.55	
Iį	V _I = 5.5 V or GND	0 to 5.5 V			±1	μΑ
I _{OZ}	$V_O = V_{CC}$ or GND	5.5 V			±5	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			20	μΑ
l _{off}	$V_I \text{ or } V_O = 0 \text{ to } 5.5 \text{ V}$	0			5	μΑ
Ci	V _I = V _{CC} or GND	3.3 V		2.9		pF



SN74LV374A-Q1 OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH 3-STATE OUTPUTS

SCLS468C - FEBRUARY 2003 - REVISED JANUARY 2008

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

		T _A = 25°C				
		MIN	MAX	MIN	MAX	UNIT
t _W	Pulse duration, CLK high or low	5		5.5		ns
t _{su}	Setup time, data before CLK↑	4.5		4.5		ns
th	Hold time, data after CLK↑	2		2		ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

		$T_A = 2$	25°C	MINI	MAY	LINUT
		MIN	MAX	MIN	MAX	UNIT
t _W	Pulse duration, CLK high or low	5		5		ns
t _{su}	Setup time, data before CLK↑	3		3		ns
th	Hold time, data after CLK↑	2		2		ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	LOAD	T,	4 = 25°C	;	NAIN!	MAY	
	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	UNIT
f _{max}				55	110		50		MHz
^t pd	CLK	Q			8.3	16.2	1	18.5	
t _{en}	ŌĒ	Q	C _L = 50 pF		7.7	14.5	1	17.5]
^t dis	ŌE	Q			5.9	14	1	16	ns
t _{sk(o)}						1.5			

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	LOAD	T,	4 = 25°C	;		MAY	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	UNIT
f _{max}				85	170		75		MHz
t _{pd}	CLK	Q			5.9	10.1	1	13.5	
t _{en}	ŌĒ	Q	C _L = 50 pF		5.5	9.6	1	13	
t _{dis}	ŌĒ	Q]		4	8.8	1	10	ns
t _{sk(o)}						1			

SN74LV374A-Q1 **OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOP** WITH 3-STATE OUTPUTS SCLS468C - FEBRUARY 2003 - REVISED JANUARY 2008

noise characteristics, V_{CC} = 3.3 V, C_L = 50 pF, T_A = 25°C (see Note 5)

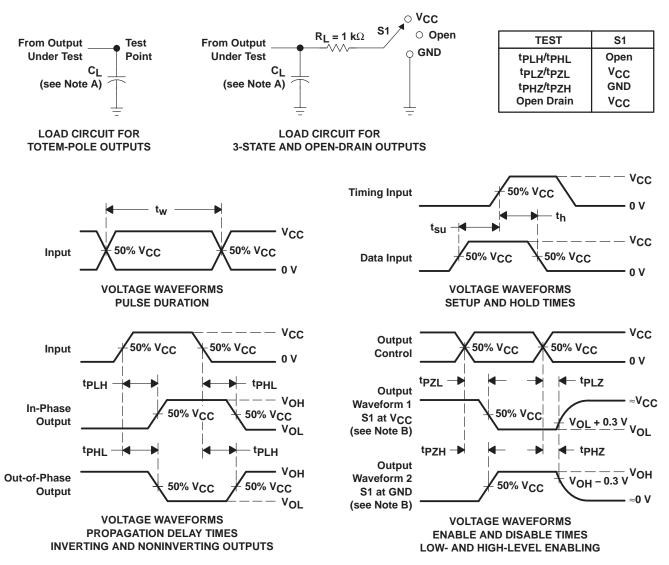
	PARAMETER	MIN	TYP	MAX	UNIT
V _{OL(P)}	Quiet output, maximum dynamic V _{OL}		0.6	0.8	V
V _{OL(V)}	Quiet output, minimum dynamic V _{OL}		-0.5	-0.8	V
VOH(V)	Quiet output, minimum dynamic VOH		2.9		V
V _{IH(D)}	High-level dynamic input voltage	2.31			V
V _{IL(D)}	Low-level dynamic input voltage			0.99	V

NOTE 5: Characteristics are for surface-mount packages only.

operating characteristics, $T_A = 25^{\circ}C$

PARAMETER			TEST CO	VCC	TYP	UNIT	
<u> </u>	Down discinsting conscitones	Outpute enabled	C. F0 pF	f = 10 MHz	3.3 V	21.1	pF
Cpd	Power dissipation capacitance	Outputs enabled $C_L = 50 \text{ pF}$,		1 = 10 WITZ	5 V	22.8	pr

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- All input pulses are supplied by generators having the following characteristics: $PRR \le 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_f \le 3 \text{ ns}$, $t_f \le 3 \text{ ns}$.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. tpz and tpzH are the same as ten.
- G. tpHL and tpLH are the same as tpd.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms







v.ti.com 18-Sep-2008

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins F	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LV374ATPWRG4Q1	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV374ATPWRQ1	ACTIVE	TSSOP	PW	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN74LV374A-Q1:

Catalog: SN74LV374A

Enhanced Product: SN74LV374A-EP

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Enhanced Product Supports Defense, Aerospace and Medical Applications

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products Amplifiers amplifier.ti.com Data Converters dataconverter.ti.com DSP dsp.ti.com Clocks and Timers www.ti.com/clocks Interface interface.ti.com Logic logic.ti.com Power Mgmt power.ti.com Microcontrollers microcontroller.ti.com www.ti-rfid.com RF/IF and ZigBee® Solutions www.ti.com/lprf

Applications	
Audio	www.ti.com/audio
Automotive	www.ti.com/automotive
Broadband	www.ti.com/broadband
Digital Control	www.ti.com/digitalcontrol
Medical	www.ti.com/medical
Military	www.ti.com/military
Optical Networking	www.ti.com/opticalnetwork
Security	www.ti.com/security
Telephony	www.ti.com/telephony
Video & Imaging	www.ti.com/video
Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2008, Texas Instruments Incorporated